

8-pin DFN Package with Reduced Exposed Pad Size Recommended for New Designs

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Everspin's Serial Peripheral Interface (SPI) MRAM is now qualified in a revised 8-pin DFN package option with a smaller exposed pad. The new package option will use the DF suffix designation in the Everspin part numbering scheme.

The new DF package option contains the same die as the existing DC package option. All products packaged in the DF option will meet the same electrical, dimensional and temperature specifications as products in the DC option. The exposed pad on the DF package is 2.0 x 2.0 mm nominal vs. 4.1 x 4.1 mm nominal for the DC package. The smaller exposed pad size significantly reduces the risk of solder bridging from pad to land without affecting product performance.

The DF package option will not immediately replace the existing DC suffix package option 8-pin DFN package. However, Everspin recommends that designers specify the new DF package option on all new designs.

For technical details about the packages, please refer to our data sheets for the SPI product family of Serial MRAMs at <http://everspin.com/products.php?hjk=SERIAL&a1f3=0>.

For more information about our 8-pin DFN package compatibility with SOIC and other DFN package layouts, refer to our Application Note: [EVERSPIN's New 2mm Exposed Pad DFN Package Meets Both SOIC-8 and DFN8 PCB Layout](#).

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